

Product Specification

产品规格书

Customer Name:

客户名称

Customer P/N:

客户料号

Product Name:

产品名称

晶体管光耦

Product P/N:

产品型号

MT-816(ABCD)

Sending Date:

制定日期

2026/04/15

| | | | | | |
|---|--|------------------------------------|---------------------------|---|--------------------|
| <input type="checkbox"/> Technical Reference 技术参考 | | <input type="checkbox"/> Sample 样品 | | <input checked="" type="checkbox"/> Mass Product 量产供货 | |
| Customer approval 客户审核 | | | Supplier approval 供方审核 | | |
| Approved 核准 | Audit 确认 | Confirmation 制作 | Approved 核准 | Audit 确认 | Confirmation 制作 |
| <input type="checkbox"/> Qualified 接受 | <input type="checkbox"/> Disqualified 不接受 | | Date: 日期: | | |



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
SENSITIVE DEVICES

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Photocoupler Model No.: MT-816(ABCD)

Features:

- Current transfer ratio (50%~600% at $I_F=5\text{mA}$; $V_{ce}=5\text{V}$)
- High input-output isolation voltage($V_{iso}= 5000\text{Vrms}$)
- Response time (t_r : typ.4 μs at $V_{CE} = 2\text{V}$, $I_C = 2\text{mA}$, $R_L = 100\ \Omega$)
- ESD pass (HBM8000V/MM2000V)
- MSL class1
- Safety approval

UL 1577

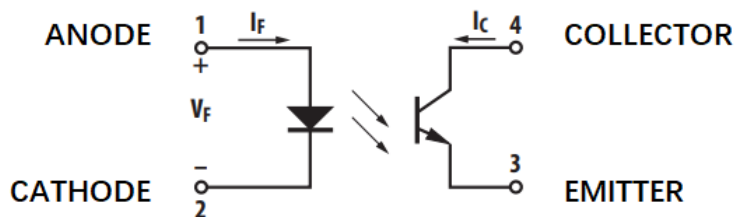
VDE

- RoHS compliance

Applications:

- Hybrid substrates that require high density mounting
- Programmable controllers

Functional Diagram



Absolute Maximum Ratings**(Ta=25°C)**

| | Parameter | Symbol | Rating | Unit |
|--------|--|-----------|----------|-----------|
| Input | Forward Current | I_F | 50 | mA |
| | Reverse Voltage | V_R | 6 | V |
| | Power Dissipation | P | 70 | mW |
| | Peak Forward Current (100 μ s pulse, 100Hz frequency) | IFP | 1 | A |
| Output | Collector - Emitter Voltage | V_{CEO} | 80 | V |
| | Emitter - Collector Voltage | V_{ECO} | 6 | V |
| | Collector Current | I_C | 50 | mA |
| | Collector Power Dissipation | P_C | 150 | mW |
| | Total Power Dissipation | P_{tot} | 200 | mW |
| | Isolation Voltage | V_{iso} | 5000 | V_{rms} |
| | Operating Temperature | T_{opr} | -55~+110 | °C |
| | Storage Temperature | T_{stg} | -55~+150 | °C |
| | Soldering Temperature | T_{sol} | 260 | °C |

AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side
- (2) The isolation voltage tester with zero-cross circuit shall be used
- (3) The waveform of applied voltage shall be a sine wave

Electrical / Optical Characteristics

(Ta=25°C)

| | Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--------------------------|--------------------------------------|---------------|---|--------------------|--------------------|------|----------|
| Input | Forward Voltage | V_F | $I_F=20mA$ | - | 1.2 | 1.4 | V |
| | Reverse Current | I_R | $V_R=4V$ | - | - | 10 | μA |
| | Terminal Capacitance | C_t | $V=0, f=1KHz$ | - | 30 | 250 | pF |
| Output | Collector Dark Current | I_{CEO} | $V_{CE}=20V, I_F=0$ | | | 100 | nA |
| | Collector-Emitter Breakdown Voltage | BV_{CEO} | $I_C=0.1mA, I_F=0$ | 80 | - | - | V |
| | Emitter-Collector Breakdown Voltage | BV_{ECO} | $I_E=10\mu A, I_F=0$ | 6 | - | - | V |
| TRANSFER CHARACTERISTICS | Collector Current | I_C | $I_F=5mA, V_{CE}=5V$ | 2.5 | - | 30 | mA |
| | *Current Transfer Ratio | CTR | $I_F=5mA, V_{CE}=5V$ | 50 | - | 600 | % |
| | Collector-Emitter Saturation Voltage | $V_{CE(Sat)}$ | $I_F=20mA, I_C=1mA$ | - | 0.1 | 0.2 | V |
| | Isolation Resistance | R_{iso} | DC500V, 40 ~ 60% R.H. | 5×10^{10} | 1×10^{11} | - | Ω |
| | Floating Capacitance | C_f | $V=0, f=1MHz$ | - | 0.6 | 1 | pF |
| | Cut-off Frequency | f_c | $V_{CE}=5V, I_C=2mA$ $R_L=100\Omega, -3dB$ | - | 80 | - | kHz |
| | Response Time (Rise) | t_r | $V_{CE}=2V, I_C=2mA$ $R_L=100\Omega$ | - | 4 | 18 | μs |
| | Response Time (Fall) | t_f | | - | 3 | 18 | μs |

$CTR = I_C / I_F * 100\%$

| CTR Rank | Min | Max | Condition |
|---------------|-----|-----|----------------------|
| A | 80 | 160 | $I_F=5mA; V_{ce}=5V$ |
| B | 130 | 260 | $I_F=5mA; V_{ce}=5V$ |
| C | 200 | 400 | $I_F=5mA; V_{ce}=5V$ |
| D3 | 300 | 450 | $I_F=5mA; V_{ce}=5V$ |
| D | 300 | 600 | $I_F=5mA; V_{ce}=5V$ |
| None Or Other | 50 | 600 | $I_F=5mA; V_{ce}=5V$ |

CHARACTERISTICS CURVES

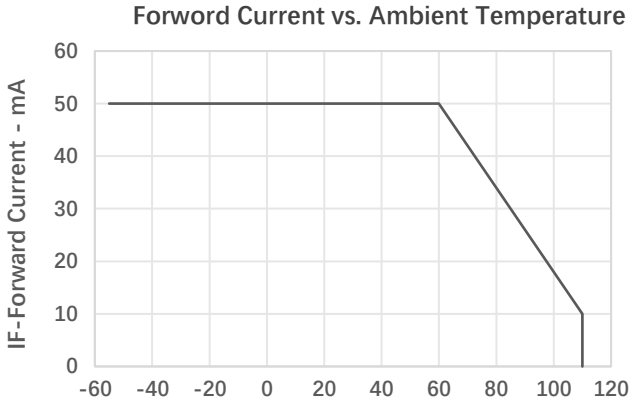


Figure 1. T_A -Ambient Temperature - °C

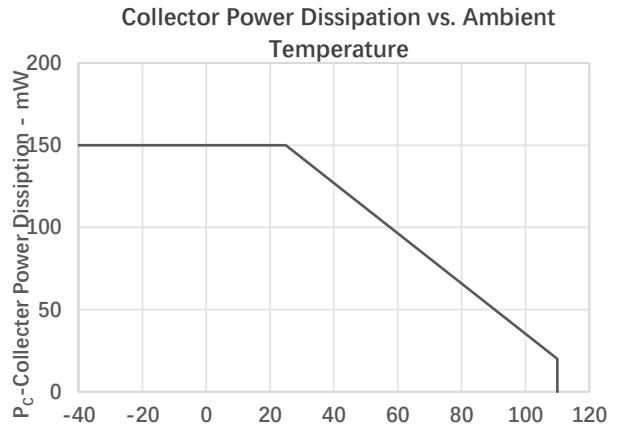


Figure 2. T_A - Ambient Temperature - °C

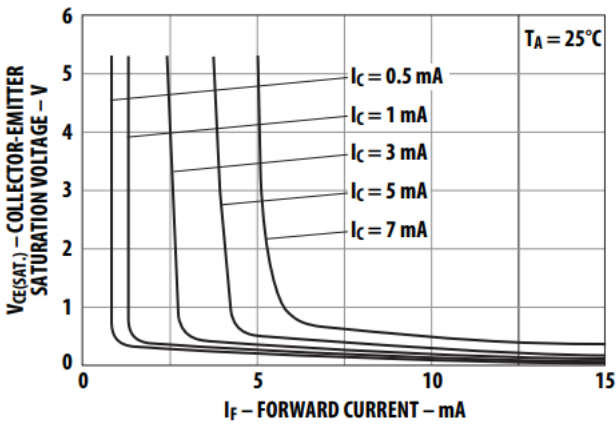


Figure 3. Collector-emitter saturation voltage vs. forward current.

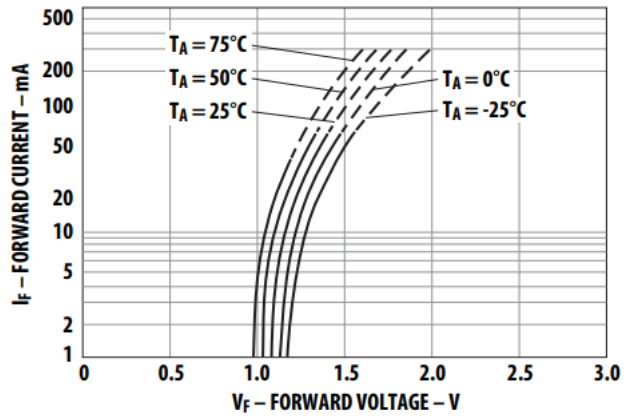


Figure 4. Forward current vs. forward voltage.

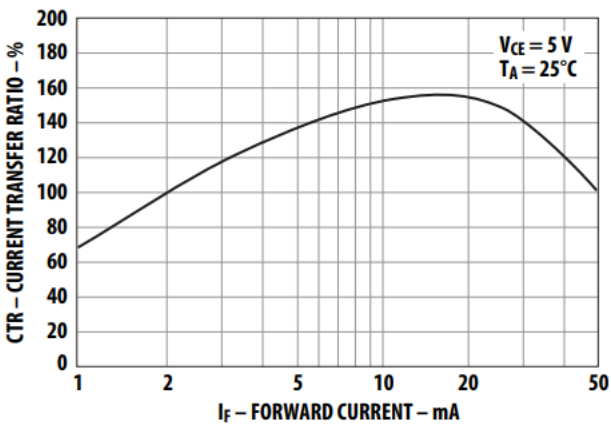


Figure 5. Current transfer ratio vs. forward current.

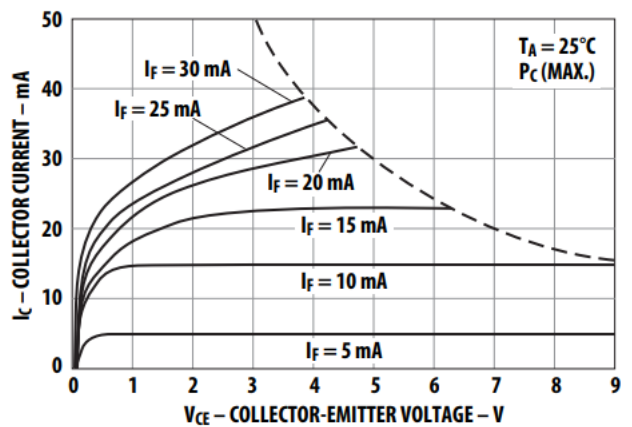


Figure 6. Collector current vs. collector-emitter voltage.

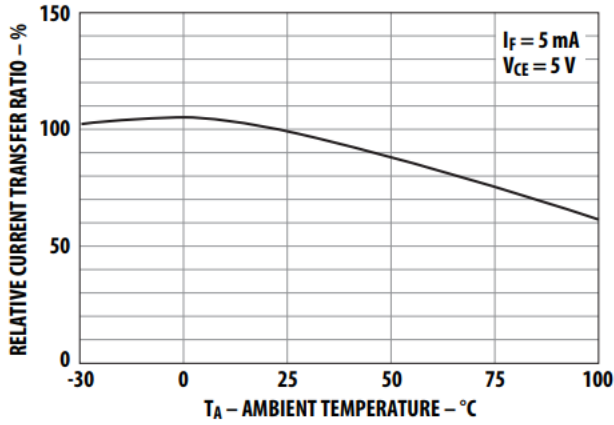


Figure 7. Relative current transfer ratio vs. temperature.

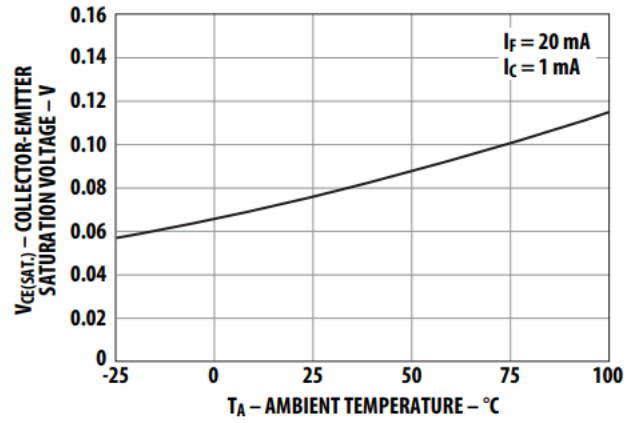


Figure 8. Collector-emitter saturation voltage vs. temperature.

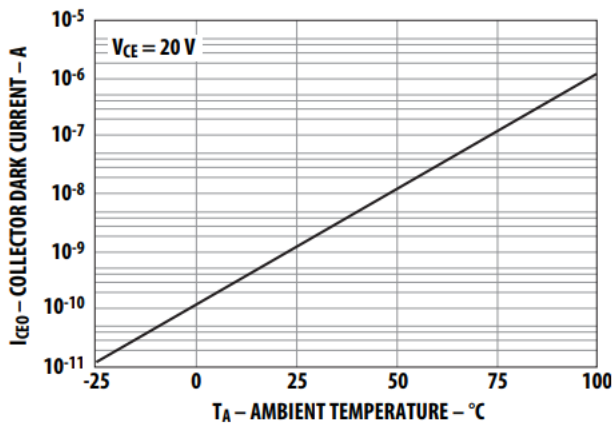


Figure 9. Collector dark current vs. temperature.

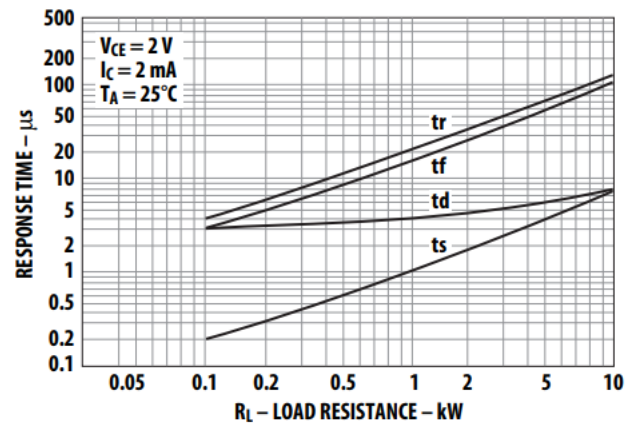


Figure 10. Response time vs. load resistance.

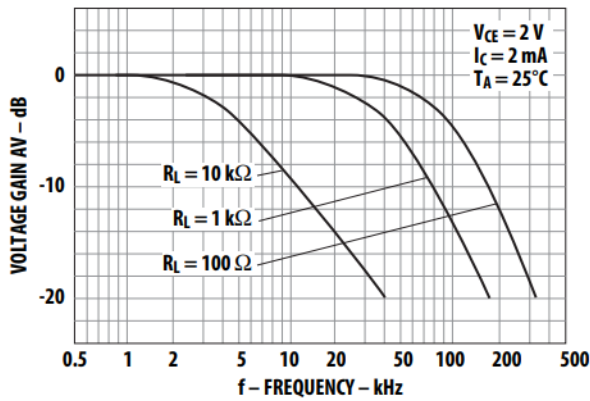
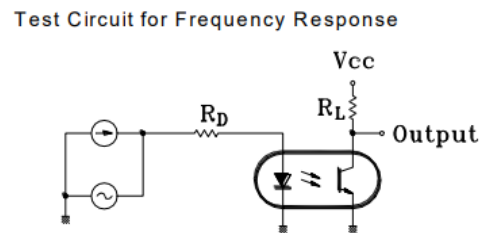
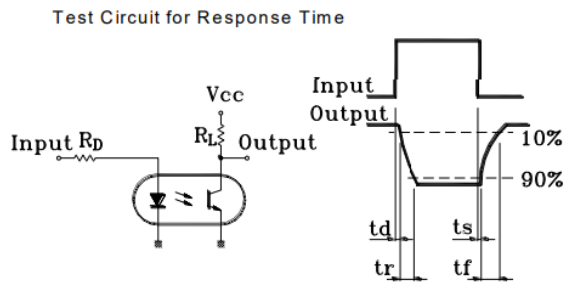


Figure 11. Frequency response.



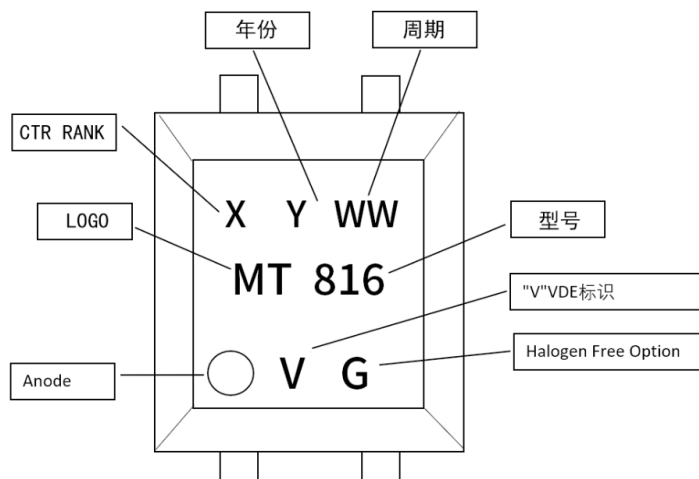
Naming Rule

MT-816-X-Y-WW-V-G

- MT---Logo
- 816---Part Number
- (X)---Representative: ABCD
- (Y)---Product Year
- (WW)---product lifecycle
- (V)---VDE
- (G)---halogen-free

Example:MT-816-X-Y-WW-V-G

Marking

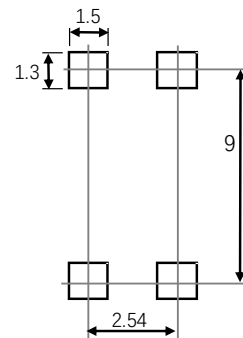
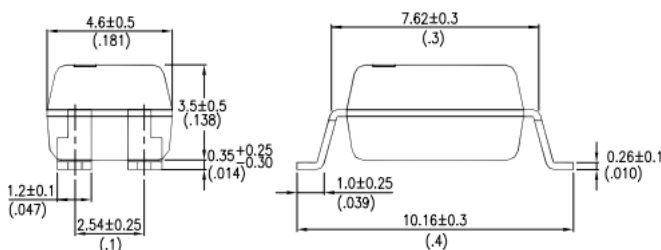


Package Dimensions

- “S”Type

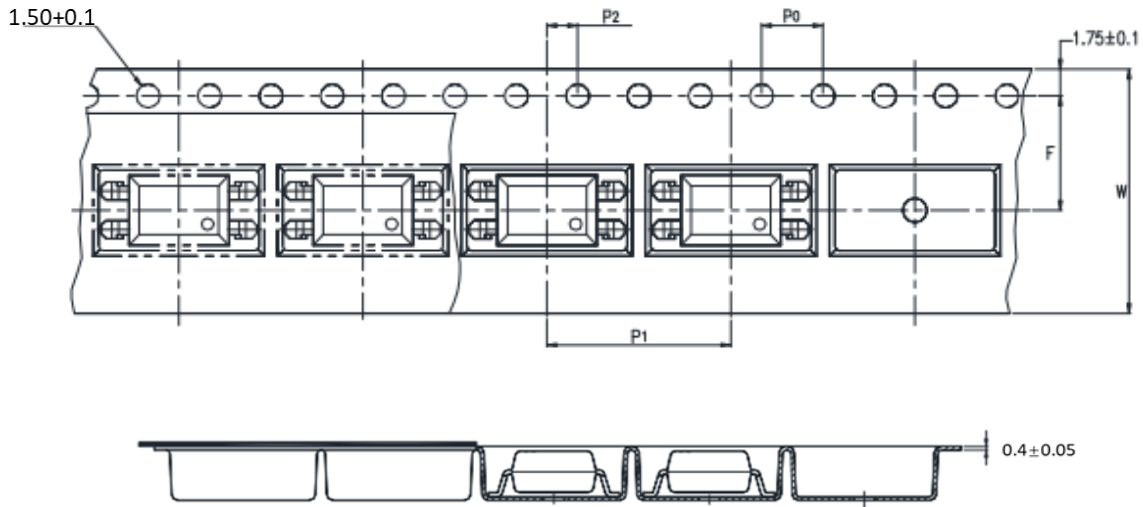
Surface mount

Surface mount (Footprint Dimensions)

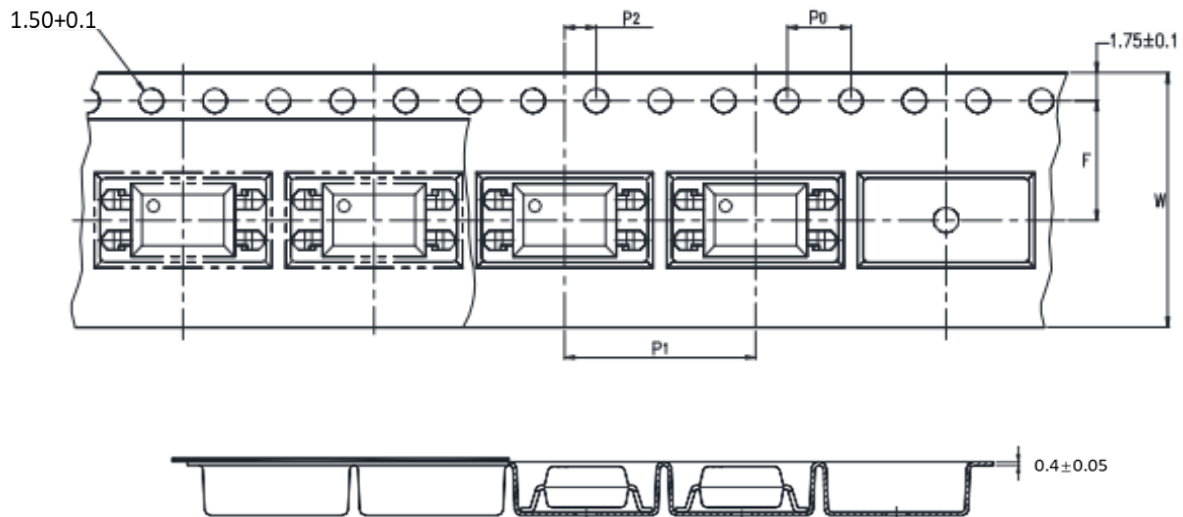


Carrier Tape Specifications

- “TA” Tape (1000 units per reel)



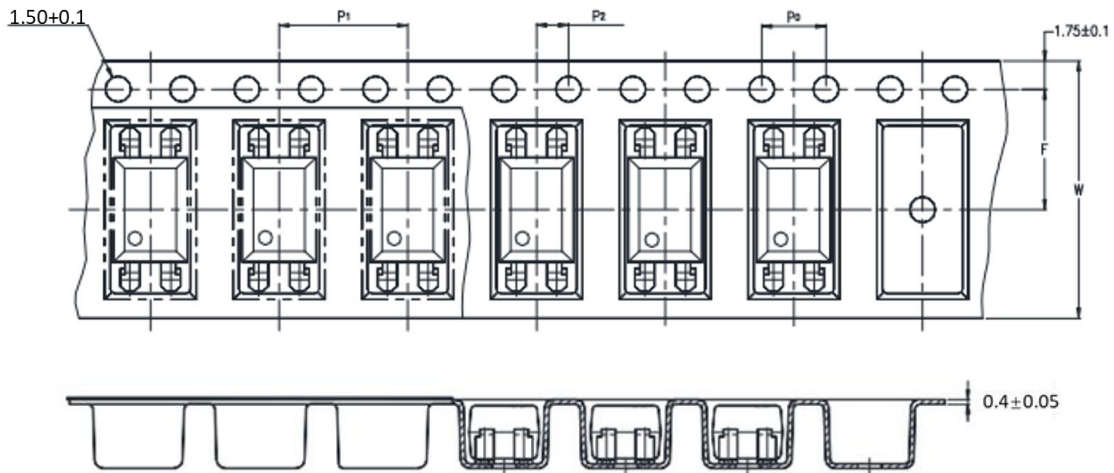
- “TA1” Tape (1000 units per reel)



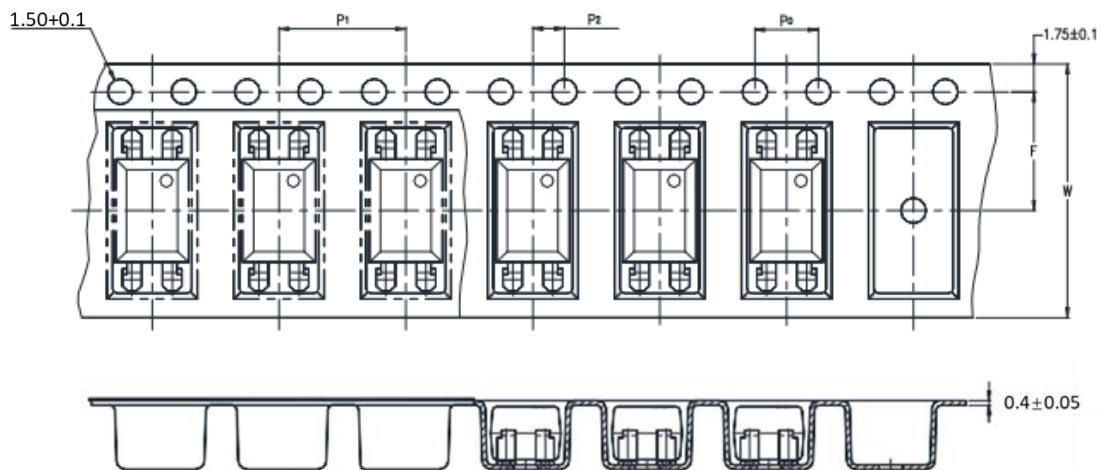
| Symbol | Description | Dimensions in mm (inches) |
|--------|--|---------------------------|
| W | Tape wide | 16 ± 0.3 (0.63) |
| P_0 | Pitch of sprocket holes | 4 ± 0.1 (0.15) |
| F | Distance of compartment | 7.5 ± 0.1 (0.295) |
| P_2 | | 2 ± 0.1 (0.079) |
| P_1 | Distance of compartment to compartment | 12 ± 0.1 (0.472) |

Carrier Tape Specifications

- “TP” Tape (2000 units per reel)

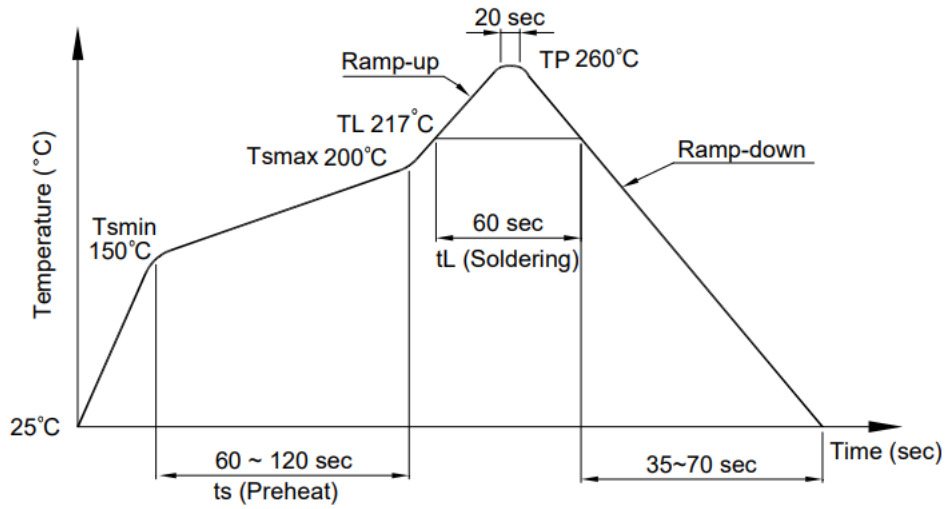


- “TP1” Tape (2000 units per reel)



| Symbol | Description | Dimensions in mm (inches) |
|--------|--|---------------------------|
| W | Tape wide | 16 ± 0.3 (0.63) |
| P_0 | Pitch of sprocket holes | 4 ± 0.1 (0.15) |
| F | Distance of compartment | 7.5 ± 0.1 (0.295) |
| P_2 | | 2 ± 0.1 (0.079) |
| P_1 | Distance of compartment to compartment | 8 ± 0.1 (0.315) |

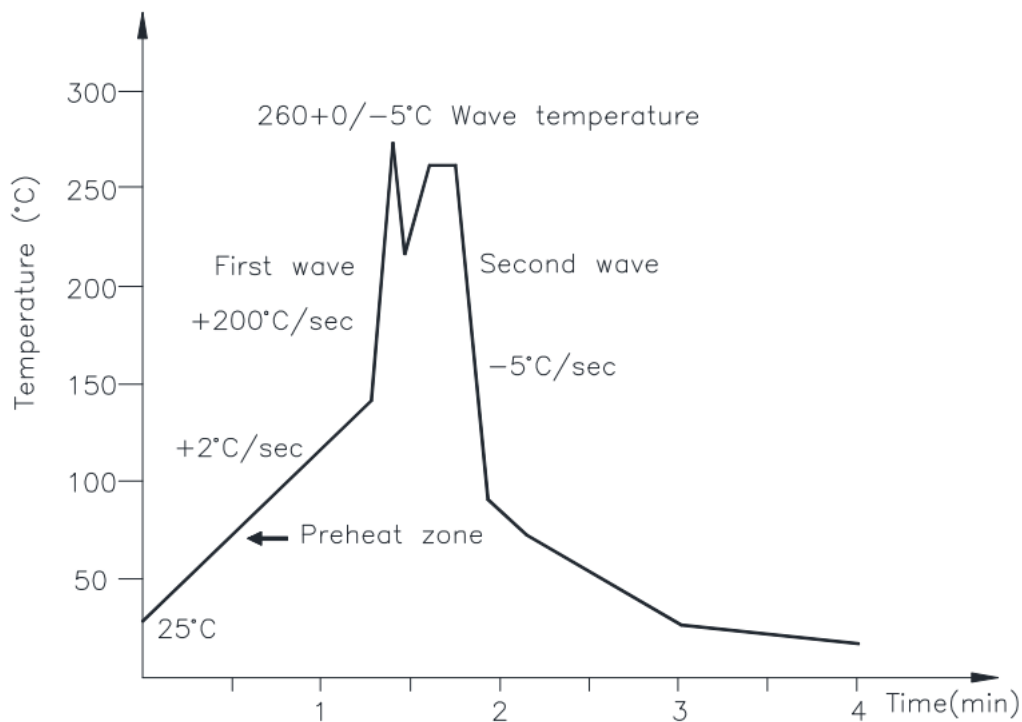
Solder Reflow Temperature Profile (JEDEC-STD-020C compliant)



| Profile Item | Conditions |
|--|---------------|
| Preheat | |
| - Temperature Min (T _{smin}) | 150°C |
| - Temperature Max (T _{smax}) | 200°C |
| - Time (min to max) (t _s) | 90±30 sec |
| Soldering zone | |
| - Temperature (T _L) | 217°C |
| - Time (t _L) | 60 sec |
| Peak Temperature (T _P) | 260°C |
| Ramp-up rate | 3°C / sec max |
| Ramp down rate | 3~6°C / sec |

One time soldering reflow is recommended within the condition of temperature and time profile shown
Do not solder more than three times

Wave Soldering (JEDEC22A111 compliant)



One time soldering is recommended within the condition of temperature

Temperature: 260+0/-5°C

Time: 10 sec

Preheat temperature: 25 to 140°C

Preheat time: 30 to 80 sec